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(12) **United States Design Patent** (10) **Patent No.:** **US D568,836 S**
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(54) **GROOVE FORMED AROUND A SEMICONDUCTOR DEVICE ON A CIRCUIT BOARD**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
174/250, 251, 253, 254, 255, 256, 265, 260,
174/261; 361/760, 748, 720; 336/200
See application file for complete search history.

(57) **CLAIM**

The ornamental design for a groove formed around a semiconductor device on a circuit board, as shown and described.

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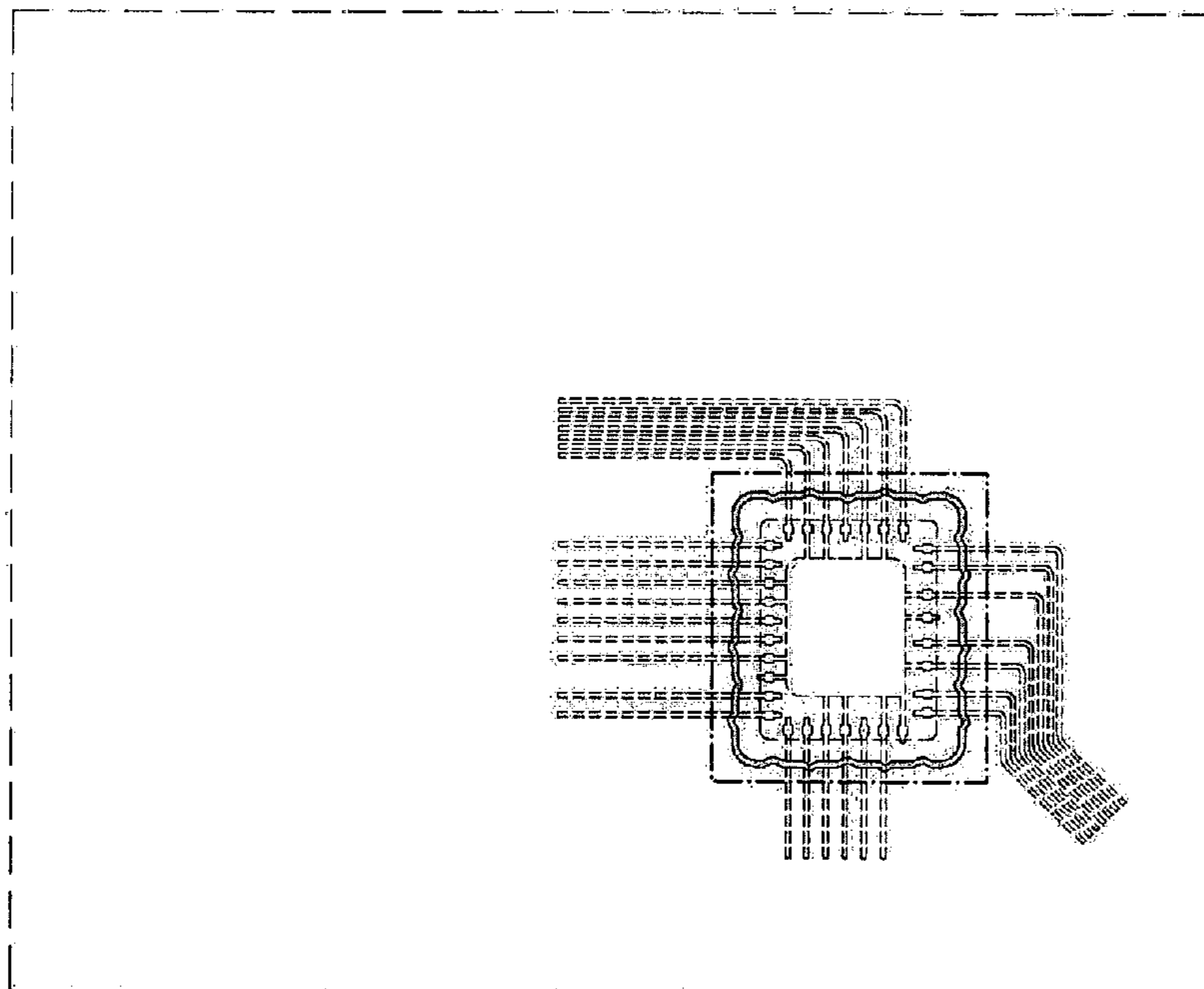
DESCRIPTION

FIG. 1 is a plan view of the groove formed around a semiconductor device on a circuit board showing our new design;

FIG. 2 is an enlarged view of the area boxed by the dash-dot-dash line in FIG. 1; and,

FIG. 3 is a sectional view taken along line 3—3 in FIG. 2. The broken lines represent unclaimed subject matter.

1 Claim, 3 Drawing Sheets



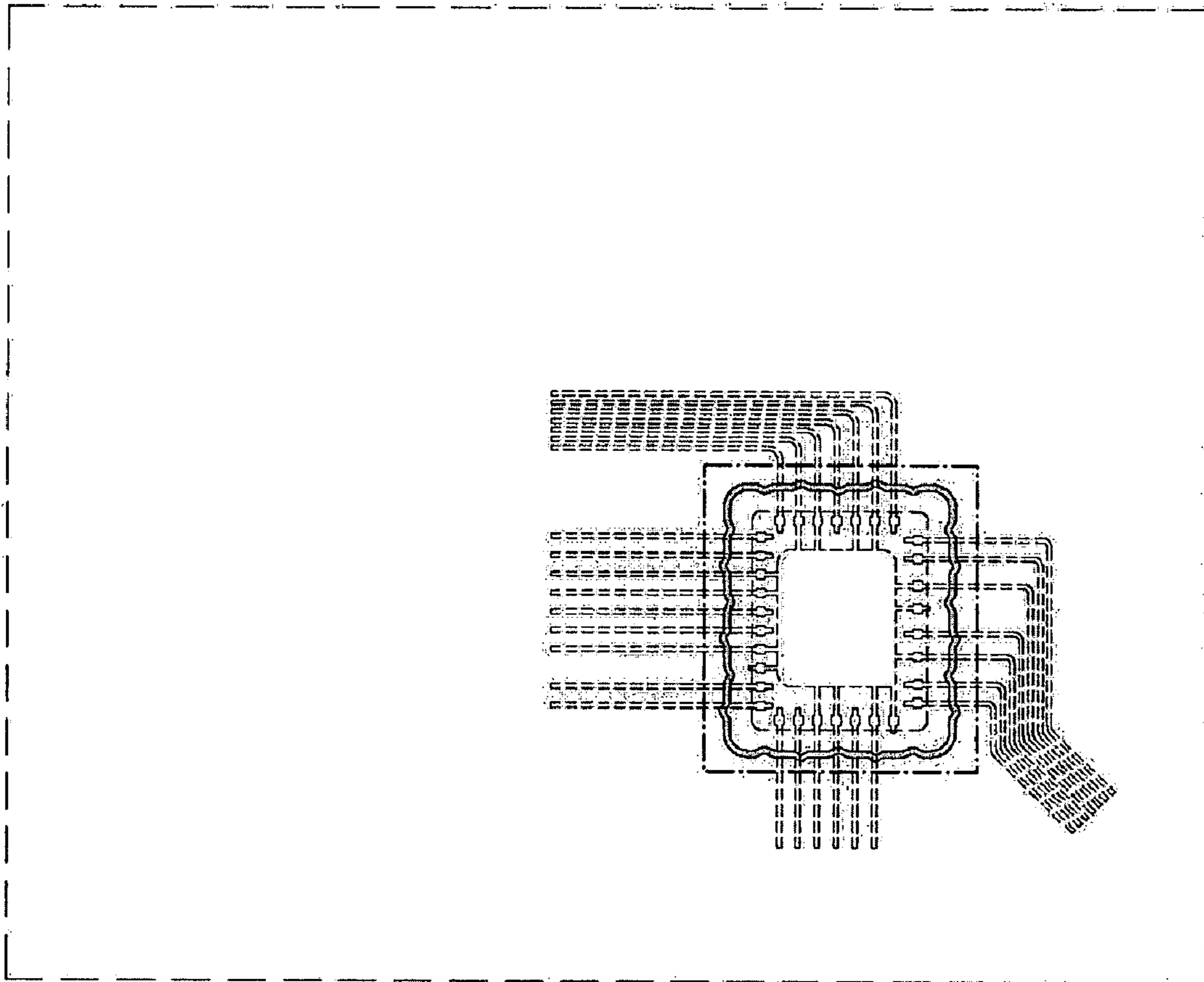


Figure 1

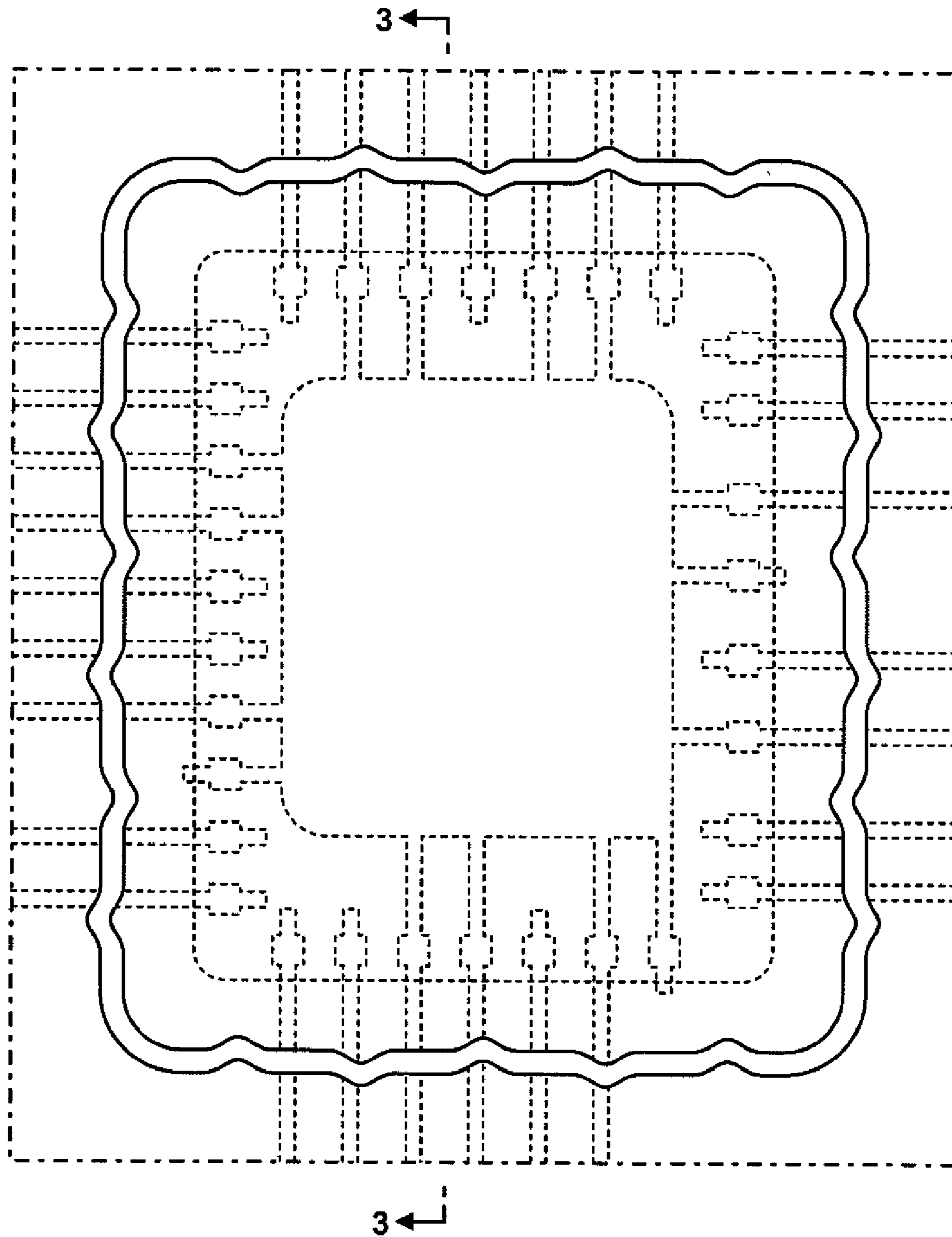


FIG. 2



FIG. 3